Technical co-sponsor

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NordPac
IMAPS Nordic Microelectronics Packaging Conference and Exhibition
8th – 10th June 2027, Quality Hotel Tønsberg, Norway

Exhibitor Opportunities at NordPac 2027

It is our pleasure to announce Exhibitor opportunities for IMAPS Nordic Microelectronics Packaging Conference and Exhibition, NordPac 2027. This is the 63rd event organised by IMAPS Nordic and is held on 8th – 10th June in **Tønsberg**, Norway.





The NordPac conference is a strong platform that brings together academics, as well as industry leaders, to discuss and debate state-of-the-art and future trends for example in the areas of **microelectronics, advanced packaging, integration, thermal management, reliability testing, PCB design, and assembly and manufacturing of electronics and optics.**

NordPac 2027 offers you a combination of interesting technical sessions with the latest news in the field and an interactive exhibition. The exhibition enables direct onsite interaction between participants. The welcome reception, coffee breaks, and the conference dinner are great platforms for networking with your academic and industry colleagues. We have received positive feedback on creating open and warm atmosphere in our events.

Exhibitor type	Price	Includes
One table	1500 €	1 participant Place at the exhibition + exhibitor presentations. Logo in Conference Booklet and NordPac website. LinkedIn post at IMAPS Nordic.
Two tables	2500 €	2 participants Place at the exhibition + exhibitor presentations. Logo in Conference Booklet and NordPac website. LinkedIn post at IMAPS Nordic.

For exhibition at NordPac 2027 please contact the Exhibition Chair Hoang-Vu Nguyen or Co-Chair Guido Sordo at info@nordpac.org.

You are warmly welcomed to exhibit at NordPac 2027!

On behalf of the organising committee,
Heidi Lundén, General Chair of NordPac 2027

LinkedIn @IMAPSNordic